

IN THE CLAIMS

Please cancel claims 14 and 24 without prejudice or disclaimer of their subject matter,
and amend claims 1 and 16, as follows:

1 1. (Currently Amended) A field emission display, comprising:
2 a first substrate;
3 an electron emission assembly arranged on said first substrate;
4 a second substrate arranged a predetermined distance from said first substrate, said
5 first and second substrates forming a vacuum space;
6 an illumination assembly arranged on said second substrate, said illumination
7 assembly being illuminated by electrons emitted from said electron emission assembly;
8 [[and]]
9 a mesh grid arranged above said electron emission assembly, the mesh grid including
10 an effective screen portion having a plurality of beam passage holes arranged in a
11 predetermined pattern and having an inactive portion absent any beam passage holes; and
12 a focusing electrode arranged on said mesh grid.

1 2. (Original) The field emission display of claim 1, wherein said mesh grid comprises
2 a metal.

1 3. (Original) The field emission display of claim 1, wherein said mesh grid comprises

2 one of stainless steel, invar, and an iron-nickel alloy.

1 4. (Original) The field emission display of claim 3, wherein the iron-nickel alloy
2 comprises 2.0 to 10.0 wt% of Cr.

1 5. (Original) The field emission display of claim 3, wherein the iron-nickel alloy
2 comprises 40.0 to 44.0 wt% of Ni.

1 6. (Original) The field emission display of claim 3, wherein the iron-nickel alloy
2 comprises 0.2 to 0.4 wt% of Mn, 0.7 wt% or less of C, and 0.3 wt% or less of Si.

1 7. (Original) The field emission display device of claim 1, wherein the thermal
2 expansion coefficient of said mesh grid is in the range of $9.0 \times 10^{-6}/^{\circ}\text{C}$ to $10.0 \times 10^{-6}/^{\circ}\text{C}$.

1 8. (Original) The field emission display device of claim 1, wherein electron emission
2 assembly comprises a cathode and a gate and an electron emission source.

1 9. (Previously Presented) The field emission display device of claim 8, wherein said
2 gate is arranged on an upper side of said cathode.

1 10. (Previously Presented) The field emission display device of claim 8, wherein the

2 gate is arranged on a lower side of said cathode.

1 11. (Original) The field emission display device of claim 1, wherein an intermediate
2 material is arranged between said electron emission assembly and said mesh grid.

1 12. (Previously Presented) The field emission display device of claim 11, wherein
2 said intermediate material comprises an insulating material.

1 13. (Previously Presented) The field emission display device of claim 11, wherein
2 said intermediate material comprises a resistive material.

Claim 14. (Canceled)

1 15. (Previously Presented) A field emission display device, comprising:
2 a first substrate;
3 an electron emission assembly arranged on said first substrate;
4 a second substrate arranged a predetermined distance from said first substrate, said
5 first and second substrates forming a vacuum assembly;
6 an illumination assembly arranged on said second substrate, said illumination
7 assembly being illuminated by electrons emitted from said electron emission assembly; and
8 a mesh grid arranged above said electron emission assembly, the mesh grid including

9 an effective screen portion having a plurality of beam passage holes arranged in a
10 predetermined pattern and having an inactive portion absent any beam passage holes;
11 wherein said mesh grid is bonded to said electron emission assembly by a frit.

1 16. (Currently Amended) A method of manufacturing a field emission display, the
2 method comprising:

3 providing a first substrate;
4 arranging an electron emission assembly on said first substrate;
5 arranging a second substrate a predetermined distance from said first substrate to form
6 a vacuum space with said first and second substrates;
7 arranging an illumination assembly on said second substrate, and illuminating said
8 illumination assembly with electrons emitted from said electron emission assembly; [[and]]
9 arranging a mesh grid above said electron emission assembly, the mesh grid including
10 an effective screen portion having a plurality of beam passage holes arranged in a
11 predetermined pattern and having an inactive portion absent any beam passage holes; and
12 a focusing electrode arranged on said mesh grid.

1 17. (Original) The method of claim 16, further comprising forming said mesh grid
2 of a metal.

1 18. (Original) The method of claim 16, further comprising forming said mesh grid

2 of one of stainless steel, invar, and an iron-nickel alloy.

1 19. (Original) The method of claim 16, further comprising forming a cathode and a
2 gate and an electron emission source in said electron emission assembly.

1 20. (Original) The method of claim 19, further comprising forming said gate on one
2 of an upper an lower side of said cathode.

1 21. (Original) The method of claim 16, further comprising forming an intermediate
2 material between said electron emission assembly and said mesh grid.

1 22. (Original) The method of claim 21, further comprising forming said intermediate
2 material of an insulating material.

1 23. (Original) The method of claim 21, further comprising forming said intermediate
2 material of a resistive material.

Claim 24. (Canceled)

1 25. (Previously Presented) A method of manufacturing a field emission display
2 device, the method comprising:

3 providing a first substrate;

4 arranging an electron emission assembly on said first substrate;

5 arranging a second substrate a predetermined distance from said first substrate to form
6 a vacuum assembly with said first and second substrates;

7 arranging an illumination assembly on said second substrate and illuminating said
8 illumination assembly with electrons emitted from said electron emission assembly;

9 arranging a mesh grid above said electron emission assembly the mesh grid including
10 an effective screen portion having a plurality of beam passage holes arranged in a
11 predetermined pattern and having an inactive portion absent any beam passage holes; and

12 bonding said mesh grid to said electron emission assembly with a frit.